

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hideki Horii	07/18/2007
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Samsung Electronics Co., Ltd.
<b>Street Address:</b>	416 Maetan-dong
<b>Internal Address:</b>	Yeongtong-gu
<b>City:</b>	Suwon-si, Gyeonggi-do
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	000
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11830284
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<b>NAME OF SUBMITTER:</b>	Michele P. McMahan
<b>Total Attachments: 2</b> source=5649_2187_Assignment#page1.tif source=5649_2187_Assignment#page2.tif	

CH \$40.00 11830284

**ASSIGNMENT**

THIS ASSIGNMENT, made by me, **Hideki Horii**, a citizen of Japan, residing at 105-1204, Hanareum Apt., Suseo-dong, Gangnam-gu, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **METHODS OF FORMING SEMICONDUCTOR DEVICES USING DI-BLOCK POLYMER LAYERS** for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, **Samsung Electronics Co., Ltd.**, a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

**ASSIGNMENT - CONTINUED**

I hereby request that said Letters Patent be issued in accordance with this assignment. I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to bind my heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this Wednes day of July, 18, 2006.

  
\_\_\_\_\_  
**Hideki Horii** (SEAL)

Witnessed by:

\_\_\_\_\_

Date: \_\_\_\_\_